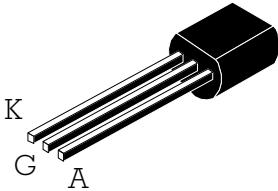
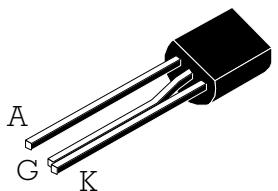


## SENSITIVE GATE SCR

<b>TO92</b> (Plastic)	<b>RD26</b> (Plastic)		
 <b>FS01...A</b>	 <b>FS01...B</b>	<b>On-State Current</b> 0.8 Amp	<b>Gate Trigger Current</b> < 200 $\mu$ A
		<b>Off-State Voltage</b> 200 V ÷ 600 V	
This series of <b>Silicon C</b> ontrolled <b>R</b> ectifiers uses a high performance PNPN technology.			
This part is intended for general purpose applications where high gate sensitivity is required.			

## Absolute Maximum Ratings, according to IEC publication No. 134

SYMBOL	PARAMETER	CONDITIONS	Min.	Max.	Unit
$I_{T(RMS)}$	On-state Current	All Conduction Angle, $T_L = 55^\circ\text{C}$	0.8		A
$I_{T(AV)}$	Average On-state Current	Half Cycle, $\alpha = 180^\circ$ , $T_L = 55^\circ\text{C}$	0.5		A
$I_{TSM}$	Non-repetitive On-State Current	Half Cycle, 60 Hz, $T_j = 25^\circ\text{C}$	8		A
$I_{TSM}$	Non-repetitive On-State Current	Half Cycle, 50 Hz, $T_j = 25^\circ\text{C}$	7		A
$I^2t$	Fusing Current	$t_p = 10\text{ms}$ , Half Cycle	0.24		$\text{A}^2\text{s}$
$V_{GRM}$	Peak Reverse Gate Voltage	$I_{GR} = 10 \mu\text{A}$	8		V
$I_{GM}$	Peak Gate Current	20 $\mu\text{s}$ max.		1	A
$P_{GM}$	Peak Gate Dissipation	20 $\mu\text{s}$ max.		2	W
$P_{G(AV)}$	Gate Dissipation	20ms max.		0.1	W
$T_j$	Operating Temperature		-40	+125	$^\circ\text{C}$
$T_{stg}$	Storage Temperature		-40	+150	$^\circ\text{C}$
$T_{sld}$	Soldering Temperature	1.6 mm from case, 10s max.		260	$^\circ\text{C}$

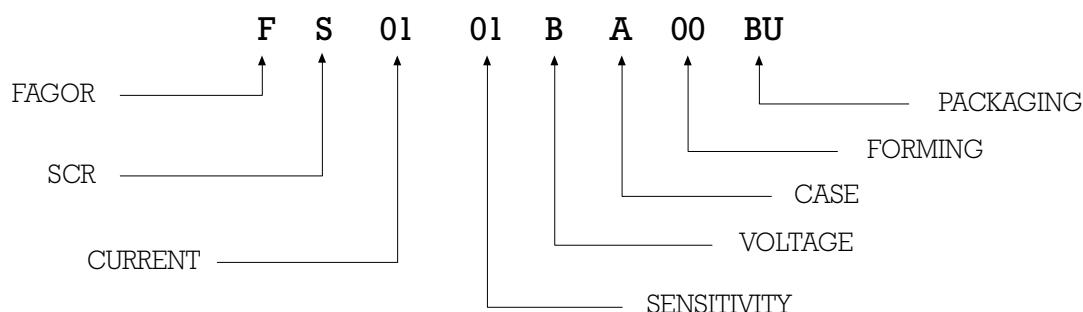
SYMBOL	PARAMETER	CONDITIONS	VOLTAGE			Unit
			B	D	M	
$V_{DRM}$	Repetitive Peak Off State Voltage	$R_{GK} = 1\text{ K}$	200	400	600	V
$V_{RRM}$						

## SENSITIVE GATE SCR

### Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	SENSITIVITY						Unit	
			01	02	03	04	11	18		
$I_{GT}$	Gate Trigger Current	$V_D = 12 \text{ V}_{DC}$ , $R_L = 140 \Omega$ , $T_j = 25^\circ\text{C}$	MIN MAX	1 20	20 200	15 50	4 25	0.5 5	$\mu\text{A}$	
$I_{DRM} / I_{RRM}$	Off-State Leakage Current	$V_D = V_{DRM}$ , $R_{GK} = 1\text{K}$ , $T_j = 125^\circ\text{C}$ $V_R = V_{RRM}$ , $T_j = 25^\circ\text{C}$	MAX MAX			100 1			$\mu\text{A}$	
$V_{TM}$	On-state Voltage	at $I_T = 1.6 \text{ Amp}$ , $t_p = 380 \mu\text{s}$ , $T_j = 25^\circ\text{C}$	MAX			1.95			V	
$V_{T(O)}$	On-state Threshold Voltage	$T_j = 125^\circ\text{C}$	MAX			0.95			V	
$r_d$	Dinamic Resistance	$T_j = 125^\circ\text{C}$	MAX			600			m	
$V_{GT}$	Gate Trigger Voltage	$V_D = 12 \text{ V}_{DC}$ , $R_L = 140 \Omega$ , $T_j = 25^\circ\text{C}$	MAX			0.8			V	
$V_{GD}$	Gate Non Trigger Voltage	$V_D = V_{DRM}$ , $R_L = 3.3\text{K}$ , $R_{GK} = 1\text{K}$ , $T_j = 125^\circ\text{C}$	MIN			0.1			V	
$I_H$	Holding Current	$I_T = 50 \text{ mA}$ , $R_{GK} = 1\text{K}$ , $T_j = 25^\circ\text{C}$	MAX			5			mA	
$I_L$	Latching Current	$I_G = 1 \text{ mA}$ , $R_{GK} = 1\text{K}$ , $T_j = 25^\circ\text{C}$	MAX			6			mA	
$dv / dt$	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$ , $R_{GK} = 1\text{K}$ , $T_j = 125^\circ\text{C}$	MIN	75	75	100	80	80	75	V/ $\mu\text{s}$
$di / dt$	Critical Rate of Current Rise	$I_G = 2 \times I_{GT}$ Tr = 100 ns, F = 60 Hz, $T_j = 125^\circ\text{C}$	MIN			50			A/ $\mu\text{s}$	
$R_{th(j-l)}$	Thermal Resistance Junction-Leads for DC					80			$^\circ\text{C/W}$	
$R_{th(j-a)}$	Thermal Resistance Junction-Ambient					150			$^\circ\text{C/W}$	

### PART NUMBER INFORMATION



## SENSITIVE GATE SCR

Fig. 1: Maximum average power dissipation versus average on-state current

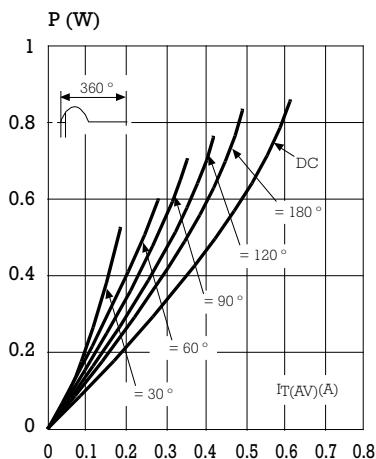


Fig. 3: Average on-state current versus lead temperature

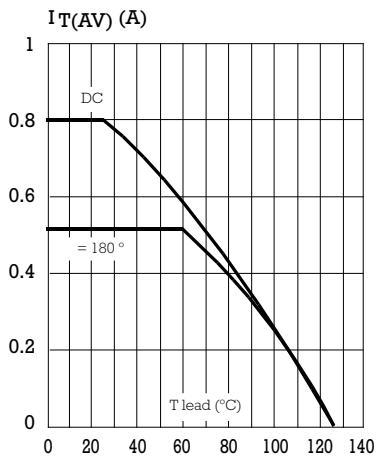


Fig. 5: Relative variation of gate trigger current and holding current versus junction temperature.

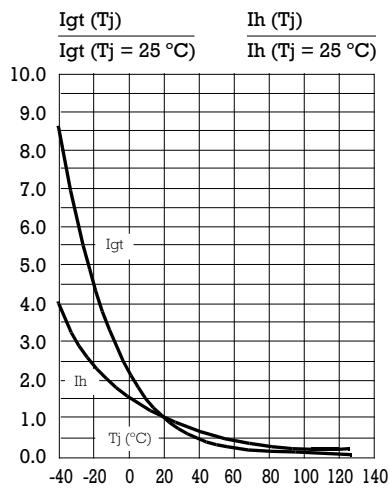


Fig. 2: Correlation between maximum average power dissipation and maximum allowable temperature (Tamb and T lead).

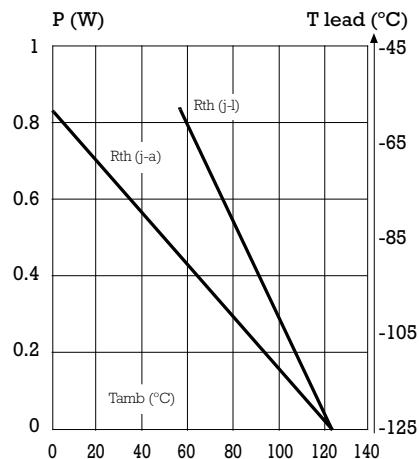


Fig. 4: Relative variation of thermal impedance junction to ambient versus pulse duration.

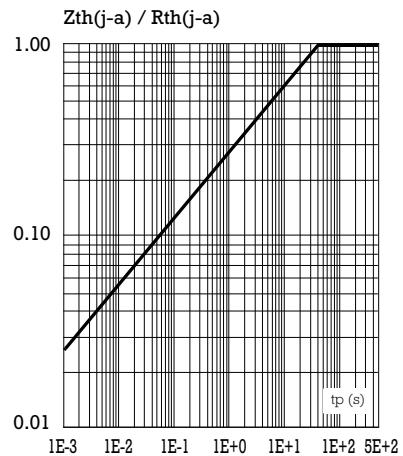
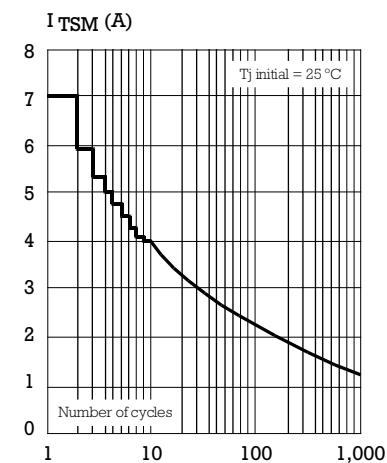


Fig. 6: Non repetitive surge peak on-state current versus number of cycles.



## SENSITIVE GATE SCR

Fig. 7: Non repetitive surge peak on-state current for a sinusoidal pulse with width:  $t_p = 10 \text{ ms}$ , and corresponding value of  $I^2 t$ .

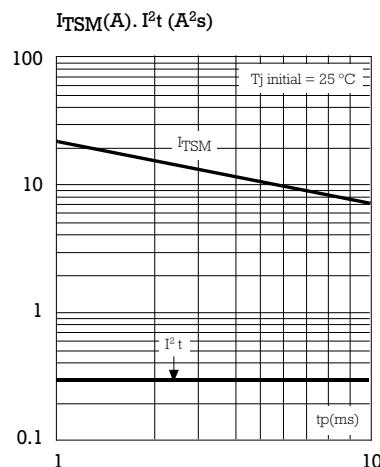


Fig. 8: On-state characteristics (maximum values).

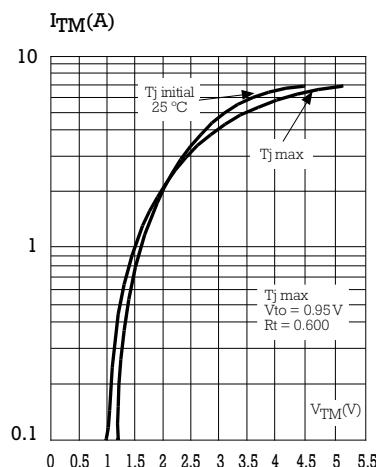
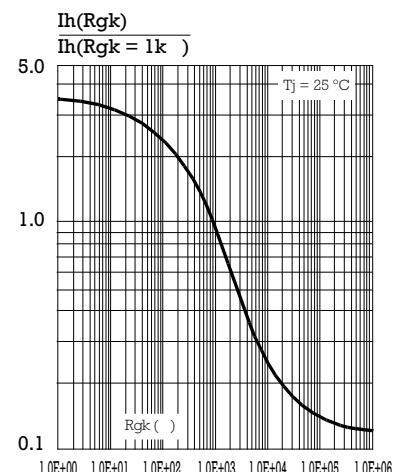


Fig. 9: Relative variation of holding current versus gate-cathode resistance (typical values).



### PACKAGE MECHANICAL DATA

TO92 (Plastic)

REF.	DIMENSIONS		
	Millimeters		
	Min.	Typ.	Max.
A	-	1.5	-
B	4.55	4.6	4.65
C	2.42	2.54	2.66
D	1.15	1.27	1.39
E	4.55	4.6	4.65
F	12.7	14.1	15.5
G	3.55	3.6	3.65
H	-	1.5	-
a	0.38	0.43	0.48
b	0.33	0.38	0.43

Marking: type number  
Weight: 0.2 g

### PACKAGE MECHANICAL DATA

RD26 (Plastic)

REF.	DIMENSIONS		
	Millimeters		
	Min.	Typ.	Max.
A	-	1.5	-
B	4.55	4.6	4.65
C	2.42	2.54	2.66
D	1.15	1.27	1.39
E	4.55	4.6	4.65
F	12.7	14.1	15.5
G	3.55	3.6	3.65
a	0.38	0.43	0.48
b	0.33	0.38	0.43

Marking: type number  
Weight: 0.2 g